

FIG._1A

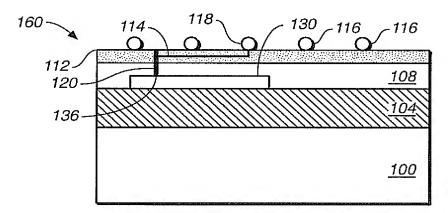


FIG._1B

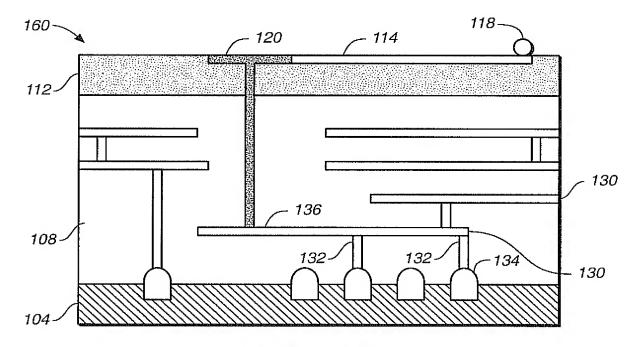


FIG._1C

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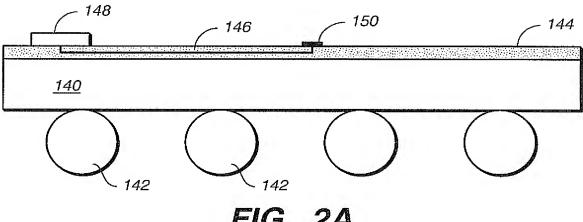
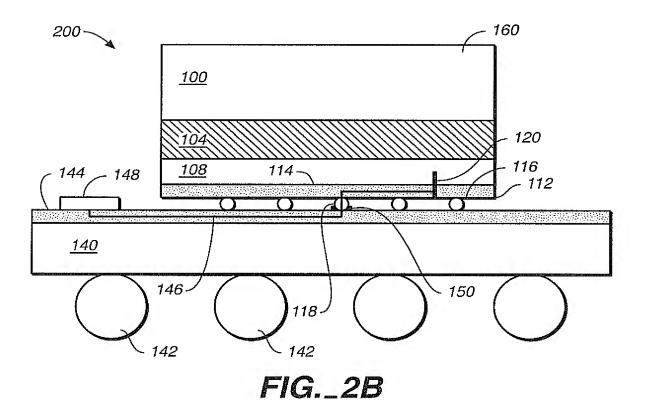


FIG._2A



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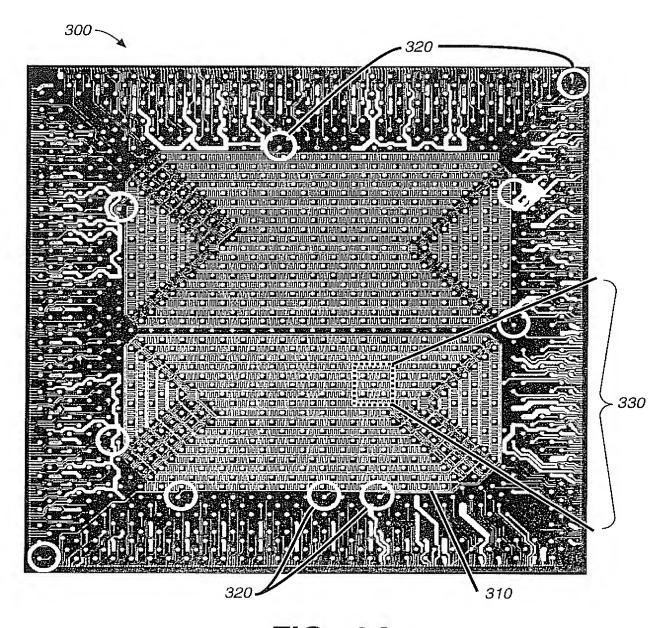


FIG._3A



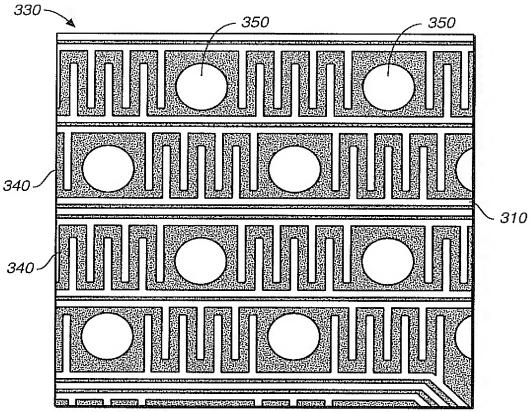
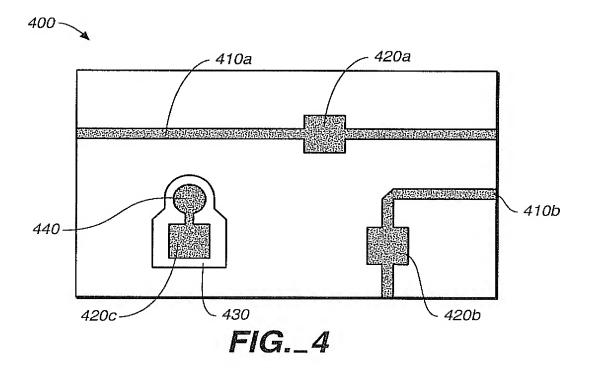


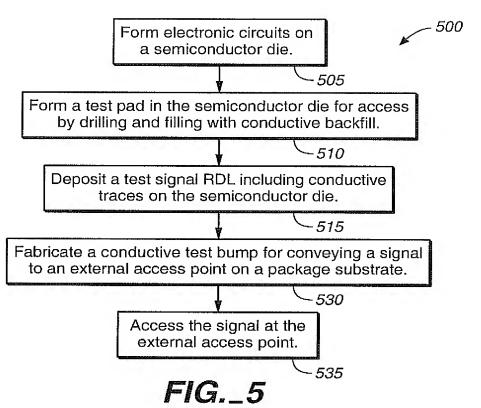
FIG._3B

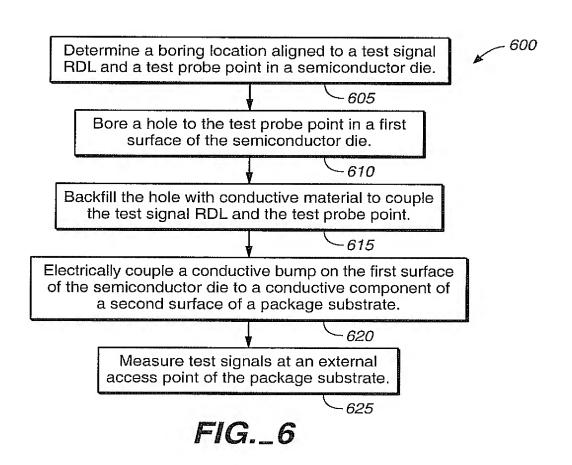


TITLE: A FLIP CHIP SEMICONDUCTOR DIE INTERNAL SIGNAL ACCESS SYSTEM AND METHOD INVENTORS: Brian S. Schieck and Howard Lee Marks

USSN: 10/789,637 Attorney Docket #: NVID-P001125 Filing Date: 02/27/04







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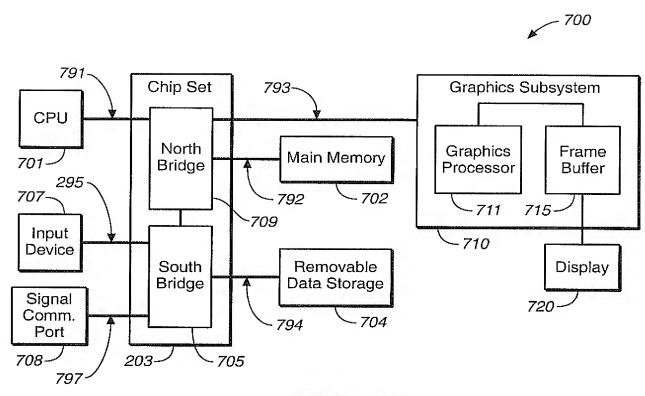


FIG._7